

CALL FOR PAPERS



2017 IEEE INTERCON

Cusco, Perú | August 15-18, 2017

The IEEE XXIV International Congress on Electronics, Electrical Engineering and Computing – INTERCON 2017 invites you to submit a full length original research contributions from engineering professionals from industries, R&D organizations, academic institutions, government departments and research scholars from across the world.

INTERCON 2017 will be held in the Imperial City of Cusco in Peru. Seductive, striking and natural, Cusco's history lives in its streets, squares, valleys and towns. Stunning destinations and examples of fine engineering by Inca stonemasons can be seen in many attractive places such as Machu Picchu, the Inca jewel built with the wisdom of the ancient Peruvians in an ecological environment.

Full length original research contributions and review articles not exceeding four pages as per the IEEE double column format shall be submitted. The manuscript should contribute original research ideas, developmental ideas, analysis, findings, results, etc. The manuscript should not have been published in any journals/magazines or conference proceedings and not under review any of them. All the submitted manuscripts will be sent for peer review and the corresponding author will be notified the outcome of the review process.

Topics: Computing, Electrical Engineering, Electronics and Communications. The topics of the conference are not limited to them.

For detailed information, please refer to the conference website: <http://intercon.org.pe/call-for-papers/>.

Submission

The official language of 2017 IEEE INTERCON is ENGLISH. Papers must be submitted in PDF and should be no longer than 4 pages, following the IEEE Conference format, available on:

http://www.ieee.org/conferences_events/conferences/publishing/templates.html

Papers can be submitted using the EasyChair System by accessing the following address:

<https://easychair.org/conferences/?conf=2017ieeeintercon>

Accepted technical and special session papers will be submitted to the IEEE Xplore Digital Library.

Important Dates

Full paper submission deadline: April 20, 2017

Notification of acceptance: June 15, 2017

Final paper submission deadline: June 30, 2017

Conference dates: August 15-18, 2017

General Chair: Santiago León-Gómez

santiago.leon@ieee.org

Program Chair: Carlos Silva-Cárdenas

csilvac@ieee.org

Information Contact: Betó Wong-Gálvez

betó.w.eng@ieee.org

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